

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD088N06N3 G	**Issued**	22. April 2022
MA#	MA005712672		
Package	PG-TO252-3-313	**Weight***	318.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.66	0.66	6647	6647
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.11	46.17	461201	461802
wire	non noble metal	aluminium	7429-90-5	3.365	1.06	1.06	10551	10551
encapsulation	inorganic material	zincoxide	1314-13-2	1.396	0.44		4377	
	miscellaneous	miscellaneous	-	6.980	2.19		21886	
	plastics	epoxy resin	-	20.941	6.57		65659	
	inorganic material	silicondioxide	60676-86-0	110.291	34.58	43.78	345802	437724
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11726	11726
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4454	4465
solder	non noble metal	tin	7440-31-5	0.044	0.01		138	
	noble metal	silver	7440-22-4	0.055	0.02		172	
	non noble metal	lead	7439-92-1	2.095	0.66	0.69	6569	6879
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60128	60206
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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